6.012 Microelectronic Devices and Circuits Spring 2005

| | March 9, 2005 Quiz #1 | |
|-----------------|--------------------------|-----------------|
| | | Problem #points |
| NAME | | 1 |
| RECITATION TIME | | 2 |
| | | 3 |
| | Тс | otal |

General guidelines (please read carefully before starting):

- Make sure to write your name on the space provided above.
- Open book: you can use any material you wish. But no computers.
- All answers should be given in the space provided. Please do not turn in any extra material.
- You have 120 minutes to complete the quiz.
- Make reasonable approximations and *state them*, i.e. low-level injection, extrinsic semiconductor, quasi-neutrality, etc.
- Partial credit will be given for setting up problems without calculations. NO credit will be given for answers without reasons.
- Use the symbols utilized in class for the various physical parameters, i.e. $N_a,\,\tau,\,\epsilon,\,$ etc.
- Pay attention to problems in which *numerical answers* are expected. An algebraic answer will not accrue full points. Every numerical answer must have the proper *units* next to it. Points will be subtracted for answers without units or with wrong units. In situations with a defined axis, the *sign* of the result is also part of the answer.

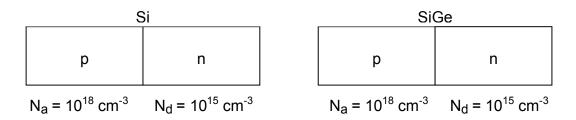
Unless otherwise stated, use:

q = 1.6 X 10⁻¹⁹ C kT/q = 25 mV at room temperature $n_i = 10^{10} \text{ cm}^{-3}$ for silicon at room temperature $\varepsilon_{si} = 10^{-12} \text{ F/cm} \quad \varepsilon_{ox} = 3.45 \text{X} 10^{-13} \text{ F/cm}$

1. (30 points)

Consider two pn-junction diodes that have identical uniform doping profiles, but differ in substrate – one is made of silicon, and one is made of a silicon-germanium alloy (SiGe). Assume the intrinsic carrier concentration for SiGe at room temperature is

approximately 10^{13} cm⁻³ and ε_{SiGe} = 1.5 x 10^{-12} F/cm



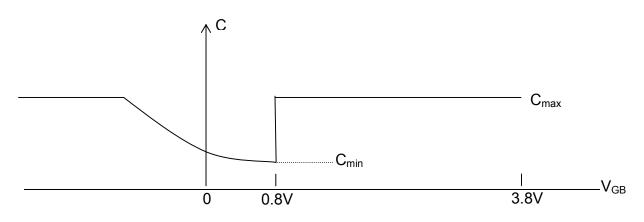
a) Calculate the built in potential for both the silicon and SiGe diodes.

b) Calculate the ratio of the depletion width on the n-side of the two diodes x_{no} in thermal equilibrium. [i.e. $x_{no}(Si)/x_{no}(SiGe)$]

c) Calculate the ratio of the electric fields at the metallurgical junction of the two diodes in thermal equilibrium. [i.e. $E_o(Si)/E_o(SiGe)$]

2. (35 Points)

An n⁺ polysilicon gate (N_d > 10²⁰ cm⁻³) MOS capacitor with p-type Si body has a capacitance-voltage plot shown below. The maximum capacitance per unit area $C_{max} = 1.7 \times 10^{-7} \text{ F/cm}^2$, while the minimum capacitance per unit area $C_{min} = 6.2 \times 10^{-8} \text{ F/cm}^2$. Assume $\phi_n^+ = 0.55 \text{ V}$.



a) What region of operation is the device in for $V_{GB} = 3.8V$?

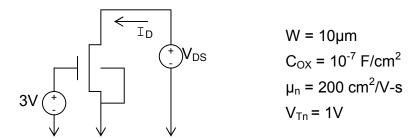
b) For the device in part (a), derive an expression for the depletion region width x_d at V_{GB} = 3.8V, in terms of C_{min} and C_{max} and fundamental parameters (e.g. q, ε_{ox} , ε_s , etc.)

c) For the device in part (a), if the magnitude of the gate charge $|Q_G| = 6.74 \times 10^{-7}$ C/cm², at V_{GB} = 3.8V, derive an expression for the doping N_a, in terms of C_{min}, C_{max} and other fundamental parameters.

d) Calculate N_a from part (c) assuming $|Q_G| = 6.74 \times 10^{-7} \text{ C/cm}^2$ and the other parameters given in (a) above:

3. (35 points)

You are given an MOS transistor with the device parameters shown below.



A drain-to-source voltage is applied resulting in the electric field at the source $E_y(0) = -3.75 \times 10^3$ V/cm and at the drain $E_y(L) = -7.5 \times 10^3$ V/cm

a) Calculate I_D .

b) Calculate the V_{DS} applied.

c) Calculate the channel length L of this device.

d) What region of operation is the transistor biased? (Circle one and explain.)
Cutoff Triode Saturation

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